	Material Comp © Copyright 2005. Il International and Par	osition Dec PC, Bannockb American co	c laration ourn, Illinois. A opyright conve	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat he declaration	ion of th encompa	e substances asses all lowe	within the ser level mate	manufacture erials for wh	er listed ite hich the m	em. Note: if anufacturer l	the item is an as has engineering	ssembly with low responsibility.	
752-21.1					Form Type Distribute						ous Materia	rials and Mfg Information				
upplie	r Information															
ompany	name*	Company unique ID			1	Unique ID Authority					Response Date*					
nsemi												2023-06-08				
ontact N	lame		Title - Contact]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*					
roduct-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item Number KA1H0165RTU		Number Mfr Item Name				Effective Date	ate Version Manufacturing Site		ing Site	v	Veight*	UOM	Unit Type		
			65RTU	FPS FOR DVDP/STB			2023-06-08 CP		СРА		2	528.3484	mg	Each		
Ianufa	cturing Proccess Informa	tion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MS	L Rating	Peak Process Body Temperat		ure Max Time at Peak Temp		Temperatu	ire Numbe	r of Reflow Cy	cles		
	Matte Tin (Sn) - annealed		U Alloy NA			0 C		30		second	ls 3					
omments	8															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.19	mg	Supplier	Silicon (Si)	7440-21-3		6.19	mg
Die Attach	1.84	mg	Supplier	Silver (Ag)	7440-22-4		0.0276	mg
			А	Lead (Pb)	7439-92-1	7a	1.7204	mg
			Supplier	Tin (Sn)	7440-31-5		0.092	mg
Lead Frame	1545.11	mg	Supplier	Silver (Ag)	7440-22-4		3.1007	mg
			Supplier	Iron (Fe)	7439-89-6		1.5503	mg
			Supplier	Copper (Cu)	7440-50-8		1539.9956	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4633	mg
Mold Compound-Black	Black 953.4	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4- hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		28.6	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		191.0003	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		23.8	mg
			Supplier	Carbon Black (C)	1333-86-4		9.534	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		700.4656	mg
Plating	21.6	mg	Supplier	Tin (Sn)	7440-31-5		21.6	mg
Wire Bond - Cu	0.2084	mg	Supplier	Palladium (Pd)	7440-05-3		0.0042	mg
			Supplier	Copper (Cu)	7440-50-8		0.2042	mg